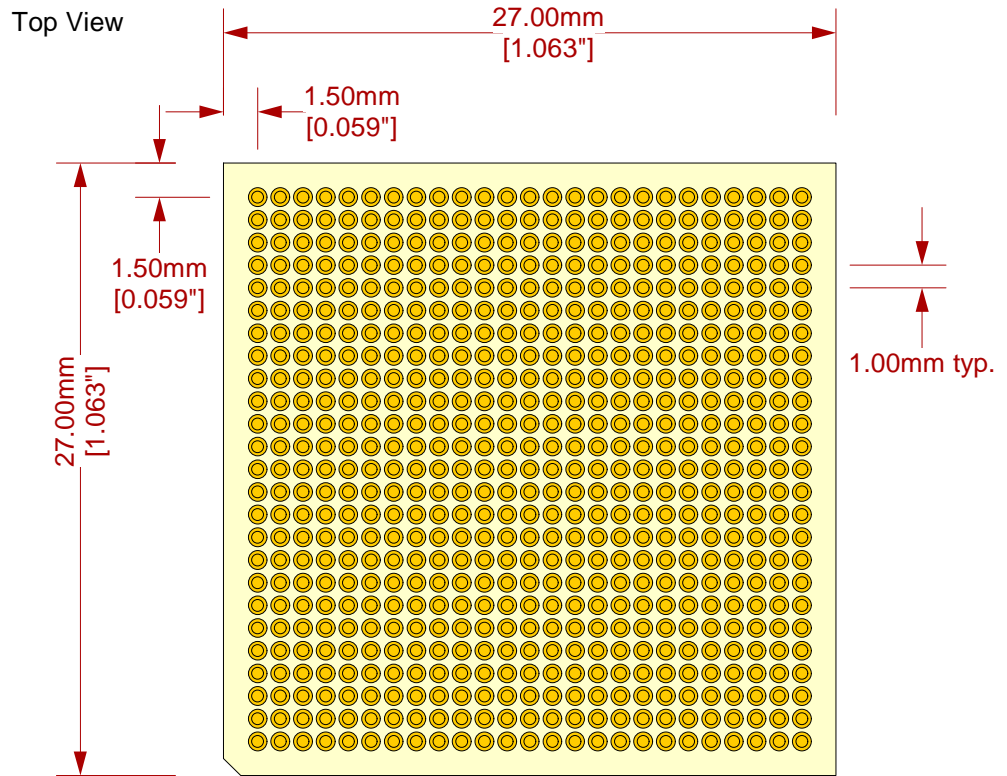


# Patent Pending

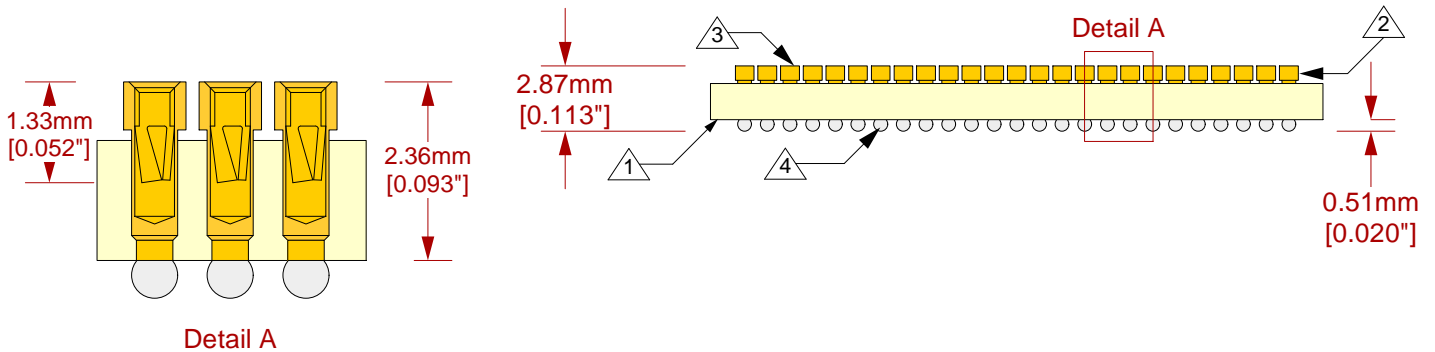
## Ordering Information:

| Solder Ball Alloy | Part Number Suffix |
|-------------------|--------------------|
| Sn63Pb37          | -42                |
| Sn96.5Ag3.0Cu0.5  | -42F*              |

\*RoHS Compliant



## Side View



### CONTACT DATA

Accepts 0.20mm - 0.33mm Diameter pins

3-finger

37/25 gram, Initial insertion force (with 0.254mm/0.203mm dia. pin)

30/22 gram, normal force (with 0.254mm/0.203mm dia. pin)


20/17 gram, extraction force (with 0.254mm/0.203mm dia. pin)

- ① Substrate: 1.59mm  $\pm$ 0.18mm [0.0625"  $\pm$ 0.007"] FR4/G10 or equivalent high temp material. (RoHS)
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 $\mu$ m [10 $\mu$ ] Au over 1.27 $\mu$ m [50 $\mu$ ] Ni (min.).
- ③ Contacts: Beryllium Copper Alloy172, HT; Finish- 0.25 $\mu$ m [10 $\mu$ ] Au over 1.27 $\mu$ m [50 $\mu$ ] Ni (min.).
- ④ Solder Balls (See table above)

### Description: Giga-snaP BGA SMT Foot

625 position (1.0mm pitch) gold plated female receptacle pins to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.18mm [ $\pm$ 0.007"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

| SF-BGA625B-B-42(F) Drawing  |                           | Status: Released | Scale: 4:1    | Rev: A |
|---|---------------------------|------------------|---------------|--------|
|  <p>© 2007 IRONWOOD ELECTRONICS, INC.<br/>11351 Rupp Dr. Ste 400 Burnsville, MN 55337<br/>Tele: (952) 229-8200<br/>www.ironwoodelectronics.com</p> | Drawing: M.A. Fedde       |                  | Date: 1/21/08 |        |
|   | File: SF-BGA625B-B-42 Dwg |                  | Modified:     |        |